

C. Remarks

The claims are 1-6 and 11-17, with claims 1, 11, 12 and 13 being independent. The independent claims have been amended to remove the features added in the Amendment filed on February 27, 2006. These features have been incorporated into new claims 14-17. No new matter has been added. Reconsideration of the present claims is expressly requested.

Applicants believe that the claims as currently amended are patentable over the cited art of record. In particular, Applicants respectfully submit that U.S. Patent Application Publication No. 2003/0026959 A1 (Furuse '959) does not disclose or suggest applying a water-soluble metallic compound to the substrate prior to the developing step or forming a precursor pattern containing at least a metallic compound.

In particular, the Examiner alleged that Furuse '959, in paragraph [0032], teaches that a water-soluble metallic compound is applied to the substrate prior to the developing step. Applicants respectfully disagree.

Paragraph [0032] discloses solutions containing metal components, as is further evidenced by this paragraph being in section (2) entitled "Solution Containing Metal Components." There is no disclosure in paragraph [0032], or elsewhere in Furuse '959, that this solution is applied to the substrate prior to developing the photosensitive resin.

In fact, the solution containing metal components is disclosed as being applied subsequent to the developing step in order to carry out the absorption into the developed resin (see paragraph [0045]). In particular, Furuse '959 states in paragraph

[0045] that the “absorbing step is a step for making the resin pattern formed as described above [in paragraphs [0038] - [0044]] absorb the above-described [in paragraphs [0031] - [0037]] solution containing metal components.” Clearly, this is not a disclosure of applying a solution containing metal components prior to the developing step. Also, consequently, Furuse ‘959 does not disclose absorbing an organic metallic compound into a base pattern that already has a metallic compound in a developed pattern.

Furuse ‘155 relates to a composition for forming an electro-conductive film. While Furuse ‘155 generally teaches the use of solutions containing organometallic compounds, it does not disclose or suggestion forming a developed pattern already containing a metallic compound and then absorbing an organic metallic compound into that pattern. Thus, the disclosure in Furuse ‘955 clearly cannot be combined with that in Furuse ‘959 to motivate a skilled artisan to apply a metallic compound before and after forming the pattern.

In that connection, the Examiner’s attention is directed to Comparative Example 1 on pages 20 and 21 of the present specification. In particular, Comparative Example 1 shows that when a metallic compound is not applied before the pattern is developed, and is absorbed only subsequent to the development, peeling may occur. Such peeling was not observed when the method in accordance of the present claims was performed (see Embodiment 1). Thus, neither Furuse ‘959 nor Furuse ‘155, whether considered separately or in combination, can affect the patentability of the presently claimed invention.

Wherefore, Applicants respectfully request that the present case expediently be passed to issue.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Jason M. Okun", written over a horizontal line.

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